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Applicant: ABBOTT Art Unit: 2826

Serial No.: 09/525,105 Examiner: Williams, A.

Filed: 03/14/00 Docket: TI-28098

For: **"SEMICONDUCTOR CIRCUIT ASSEMBLY HAVING
A PLATED LEADFRAME INCLUDING GOLD SELECTIVELY
COVERING AREAS TO BE SOLDERED"**

AMENDMENT 37 CFR 1.115

June 28, 2001

Assistant Commissioner
for Patents
Washington, D.C. 20231

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Glenda West

Glenda West 06/28/01

Sir:

Responsive to the Office Action of March 28, 2001, please amend the application as follows:

Change the title to read:

**"SEMICONDUCTOR CIRCUIT ASSEMBLY HAVING A PLATED
LEADFRAME INCLUDING GOLD SELECTIVELY COVERING AREAS TO
BE SOLDERED"**

Amend the claims as follows:

Claim 1, line 3, after "covering" insert--outer--; line 4, after "attachment", insert a period-- and delete the remainder of the claim.